

Amendments to the Specification:

Please insert the following new paragraph on page 1, line 2, before the heading, Field of the Invention.

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--Related Applications:

This application is a Divisional application of Serial No. 09/430,965, filed November 1, 1999, now issued as United States Patent No. 6,347,901.--

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Please replace the paragraph beginning on page 8, line 5 with the following amended paragraph:

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--Referring to Figure 4, a solder joint at the having an intermetallic region formed between solder 25 and the pad 10 and an intermetallic boundary 15 is shown, using. The pad 10 has the serpentine solder configuration depicted in Figure 3a. It will be observed that the respective micro-cracking 20 at each intermetallic boundary 15 is following a circuitous or meandering path. The lengthening of the crack pathway increases the useful life of the solder joint. Other pad configurations are shown in Figures 3b through 3d. As before, this results in micro-crack pathways that ~~which~~ are interrupted, lengthened, or constrained. In a similar manner, these configurations are expected to increase fatigue life of the solder joint, as is that of the solder design shown in Figure 3a.--

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